



## Material Content Data Sheet



<b>Sales Product Name</b>				BSZ12DN20NS3 G		<b>Issued</b>		29. August 2013	
<b>MA#</b>				MA000862672					
<b>Package</b>				PG-TSDSON-8-2		<b>Weight*</b>		38.45 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.374	3.57	3.57	35738	35738	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		55		
	non noble metal	zinc	7440-66-6	0.008	0.02		218		
	non noble metal	iron	7439-89-6	0.168	0.44		4361		
wire	non noble metal	copper	7440-50-8	6.808	17.71	18.18	177074	181708	
	non noble metal	copper	7440-50-8	0.049	0.13	0.13	1268	1268	
	encapsulation	organic material	carbon black	1333-86-4	0.035	0.09		899	
	plastics	epoxy resin	-	1.780	4.63		46303		
	inorganic material	silicondioxide	60676-86-0	15.468	40.23	44.95	402343	449545	
leadfinish	non noble metal	tin	7440-31-5	0.387	1.01	1.01	10070	10070	
plating	noble metal	silver	7440-22-4	0.963	2.50	2.50	25038	25038	
solder	noble metal	silver	7440-22-4	0.038	0.10		991		
	non noble metal	tin	7440-31-5	0.030	0.08		793		
	non noble metal	lead	7439-92-1	1.455	3.79	3.97	37854	39638	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		28		
	non noble metal	zinc	7440-66-6	0.004	0.01		112		
	non noble metal	iron	7439-89-6	0.086	0.22		2243		
	non noble metal	copper	7440-50-8	3.501	9.11	9.34	91068	93451	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		49		
	non noble metal	zinc	7440-66-6	0.008	0.02		196		
	non noble metal	iron	7439-89-6	0.151	0.39		3925		
	non noble metal	copper	7440-50-8	6.127	15.94	16.35	159374	163544	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com